

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the present application.

Listing of Claims:

Claim 1 (currently amended): A ceramic susceptor for semiconductor manufacturing equipment, the ceramic susceptor comprising:

- a ceramic substrate, one side thereof having a wafer-retaining face;
- a resistive heating element provided either superficially or interiorly in said substrate; and
- a recess formed in said wafer-retaining face with room to carry a semiconductor manufacturing wafer, said recess including constituted by a perimetric wall and a substantially planar bottom face the entirety of which is planar, and being shaped such that the perimetric wall meets the bottom face to form an angle greater than 90° and less than 170° and so that the perimetric wall and the bottom face join in a circumferential verge having a radius of curvature of 0.1 mm or more, the bottom face being sized to receive a back side of the wafer such that the entire back side is in contact with the bottom face ~~across substantially the entire diameter of the wafer~~.

Claim 2 (previously presented): A semiconductor-manufacturing-equipment ceramic susceptor as set forth in claim 1, wherein said ceramic substrate is made of at least one selected from the group consisting of: aluminum nitride, silicon nitride, aluminum oxynitride, and silicon carbide.

Claim 3 (previously presented): A semiconductor-manufacturing-equipment ceramic susceptor as set forth in claim 1, wherein said resistive heating element is

made from at least one selected from the group consisting of: tungsten, molybdenum, platinum, palladium, silver, nickel, and chrome.

Claim 4 (previously presented): A semiconductor-manufacturing-equipment ceramic susceptor as set forth in claim 2, wherein said resistive heating element is made from at least one selected from the group consisting of: tungsten, molybdenum, platinum, palladium, silver, nickel, and chrome.

Claim 5 (original): A semiconductor-manufacturing-equipment ceramic susceptor as set forth in claim 1, further comprising a plasma electrode disposed either superficially or interiorly in said ceramic substrate.

Claim 6 (original): A semiconductor-manufacturing-equipment ceramic susceptor as set forth in claim 2, further comprising a plasma electrode disposed either superficially or interiorly in said ceramic substrate.

Claim 7 (original): A semiconductor-manufacturing-equipment ceramic susceptor as set forth in claim 3, further comprising a plasma electrode disposed either superficially or interiorly in said ceramic substrate.

Claim 8 (original): A semiconductor-manufacturing-equipment ceramic susceptor as set forth in claim 4, further comprising a plasma electrode disposed either superficially or interiorly in said ceramic substrate.

Claims 9 through 20 (canceled)